

Application Serial No. 10/800,603
Reply to Office Action of January 30, 2005

PATENT
Docket: CU-3637

Amendments To The Claims

The listing of claims presented below will replace all prior versions, and listings, of claims in the application.

Listing of claims:

1. **(currently amended)** A semiconductor device substrate, comprising:
 - a substrate body having a wiring layer;
 - a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted; and
 - a reinforcing member having two surfaces and sides,
wherein the surface areas of the reinforcing member are
larger than the opening forming portion, ~~provided~~
wherein the sides and one surface area of the
reinforcing member are embedded in said substrate body at a portion corresponding to the opening forming portion such that
only a portion of the unembedded surface is exposed through
the opening forming portion, and
a semiconductor element mounted on the surface of the reinforcing
member exposed through the opening forming portion.
~~and reinforcing said substrate body at the portion corresponding to the opening forming portion, wherein a part of the reinforcing member is exposed at a surface of the substrate body.~~

Application Serial No. 10/800,603
Reply to Office Action of January 30, 2005

PATENT
Docket: CU-3637

2. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is a circuit board having a capacitor part that electrically connects the semiconductor element and the wiring layer.
3. (original) The semiconductor device substrate as claimed in claim 2, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
4. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is an interposer having a via that directly electrically connects the semiconductor element and the wiring layer.
5. (original) The semiconductor device substrate as claimed in claim 4, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
6. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
7. (previously presented) A manufacturing method of a substrate, said manufacturing method comprising the steps of:

manufacturing a reinforcing member having two surfaces and sides;

arranging the reinforcing member on a base at a portion corresponding to an opening forming portion of the base, wherein the surface areas of the reinforcing member are larger than the opening forming portion;

forming a substrate body on the base on which the reinforcing member is arranged so that the reinforcing member is provided in said substrate, said substrate body including a wiring layer and made of a material that is different from a material of the base,

wherein the sides and one surface area of the

Application Serial No. 10/800,603
Reply to Office Action of January 30, 2005

PATENT
Docket: CU-3637

reinforcing member are embedded in said substrate body at a portion corresponding to the opening forming portion such that only a portion of the unembedded surface is exposed through the opening forming portion
mounting a semiconductor element on the surface of the reinforcing member exposed through the opening forming portion.

~~wherein a part of the reinforcing member is exposed at a surface of the substrate body; and forming the opening forming portion smaller than the reinforcing member, thereby exposing a part of the reinforcing member at the opening forming portion.~~

8. (original) The manufacturing method as claimed in claim 7, wherein the step of manufacturing the reinforcing member includes a step of forming a capacitor on a core member.

9. (previously presented) The manufacturing method as claimed in claim 7, wherein the step of manufacturing the reinforcing member includes a step of forming a via penetrating the core member.

10. (original) The manufacturing method as claimed in claim 9, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

11. (original) The manufacturing method as claimed in claim 8, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

12. (original) The manufacturing method as claimed in claim 7, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

13. (currently amended) A semiconductor device, ~~comprising:~~

Application Serial No. 10/800,603
Reply to Office Action of January 30, 2005

PATENT
Docket: CU-3637

~~the semiconductor device~~ substrate comprising:

a substrate body having a wiring layer;

a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted; and

a reinforcing member having two surfaces and sides,

wherein the surface areas of the reinforcement member

are larger than the opening forming portion, ~~provided~~

wherein the sides and one surface area of the

reinforcing member are embedded in said substrate body at a

portion corresponding to the opening forming portion such that

only a portion of the unembedded surface is exposed through

the opening forming portion, and

~~reinforcing said substrate body at the portion~~

~~corresponding to the opening forming portion, wherein a part~~

~~of the reinforcing member is exposed at a surface of the~~

~~substrate body; and~~

a semiconductor element mounted ~~in~~ on the surface of the reinforcing

member exposed through the opening forming portion ~~of the semiconductor device substrate.~~

14. (previously presented) A semiconductor device of claim 13, wherein the reinforcing member is a circuit board having a capacitor part that electrically connects

Application Serial No. 10/800,603
Reply to Office Action of January 30, 2005

PATENT
Docket: CU-3637

the semiconductor element and the wiring layer.

15. (previously presented) A semiconductor device of claim 14, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

16. (previously presented) A semiconductor device of claim 13, wherein the reinforcing member is an interposer having a via that directly electrically connects the semiconductor element and the wiring layer.

17. (previously presented) A semiconductor device of claim 16, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

18. (previously presented) A semiconductor device of claim 13, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

19. (previously presented) A semiconductor device substrate, comprising:

a substrate body having a wiring layer;

a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted; and

a reinforcing member **being having two surfaces and sides,**

wherein the surface areas of the reinforcing member are larger than the opening forming portion, **provided**

wherein the sides and one surface area of the reinforcing member are embedded in said substrate body at a portion corresponding to the opening forming portion ~~so that a part of the reinforcing member is embedded in the substrate body, and reinforcing said substrate body at the portion corresponding to the opening forming portion, wherein a part of the~~

Application Serial No. 10/800,603
Reply to Office Action of January 30, 2005

PATENT
Docket: CU-3637

~~reinforcing member is exposed at a surface of the substrate body such that~~
only a portion of the unembedded surface is exposed through the opening
forming portion, and
a semiconductor element mounted on the surface of the reinforcing
member exposed through the opening forming portion.